To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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HVU300A

Variable Capacitance Diode for Electronic Tuning

ADE-208-065D(Z)

Rev. 4
Jun. 1996

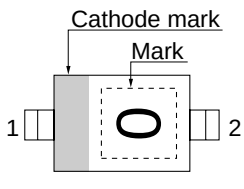
Features

- High capacitance ratio (n = 14.5min) and suitable for wide band tuner.
- Low series resistance and good C-V linearity.
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVU300A	0	URP

Outline



1. Cathode
2. Anode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	32	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_{R1}	—	—	10	nA	V_R = 30V
	I_{R2}	—	—	100		V_R = 30V, Ta = 60 °C
Capacitance	C_2	39.5	—	47.4	pF	V_R = 2V, f = 1 MHz
	C_{25}	2.60	—	3.03		V_R = 25V, f = 1 MHz
Capacitance ratio	n	14.5	—	—	—	C_2 / C_{25}
Series resistance	r_s	—	—	1.10	Ω	V_R = 5V, f = 470 MHz
Matching error	$\Delta C/C^{*1}$	—	—	2.0	%	V_R = 2 to 25V, f = 1 MHz

Note: 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of ΔC/C continuous in a reel , expect extention to another group.
Calculate Matching Error,

$$\Delta C/C = \frac{(Cmax-Cmin)}{Cmin} \times 100\ (\%)$$

Main Characteristic

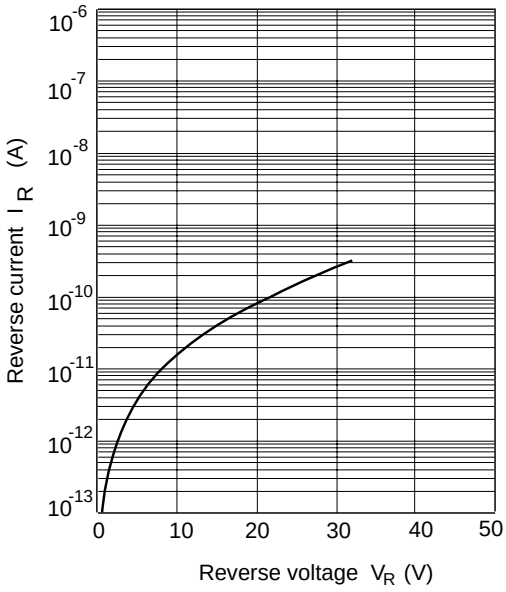


Fig.1 Reverse current Vs. Reverse voltage

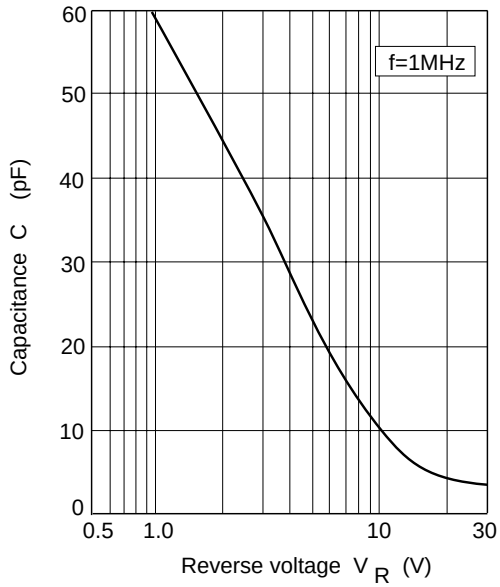


Fig.2 Capacitance Vs. Reverse voltage

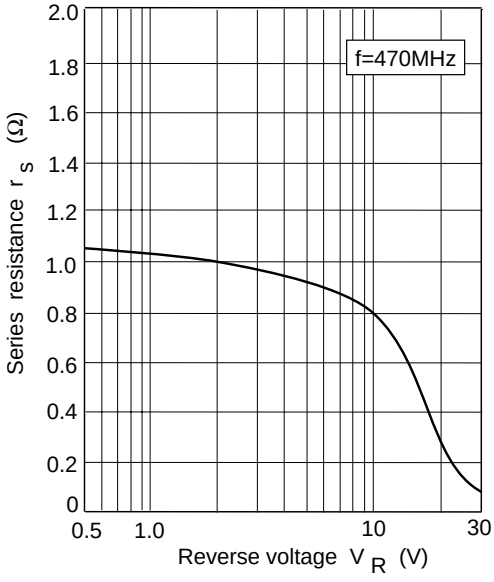


Fig.3 Series resistance Vs. Reverse voltage

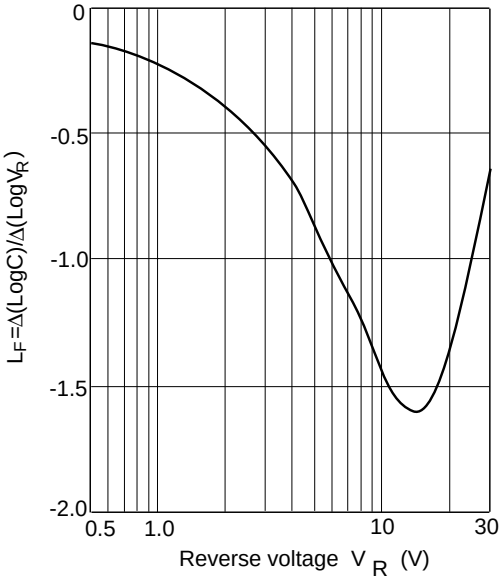
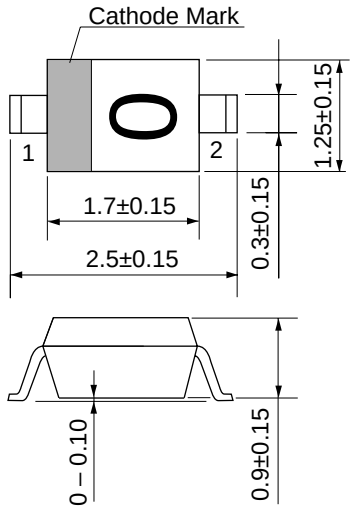


Fig.4 Linearity factor Vs. Reverse voltage

Package Dimensions

Unit : mm



1. Cathode
2. Anode

Hitachi Code	URP
JEDECCode	—
EIAJCode	—
Weight(g)	0.004

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